

# 74ALVC32

## Quad 2-input OR gate

Rev. 3 — 20 January 2014

Product data sheet

### 1. General description

The 74ALVC32 is a quad 2-input OR gate.

Schmitt trigger action on all inputs makes the device tolerant of slow rise and fall times.

### 2. Features and benefits

- Wide supply voltage range from 1.65 V to 3.6 V
- 3.6 V tolerant inputs/outputs
- CMOS low power consumption
- Direct interface with TTL levels (2.7 V to 3.6 V)
- Power-down mode
- Latch-up performance exceeds 250 mA
- Complies with JEDEC standards:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114E exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V

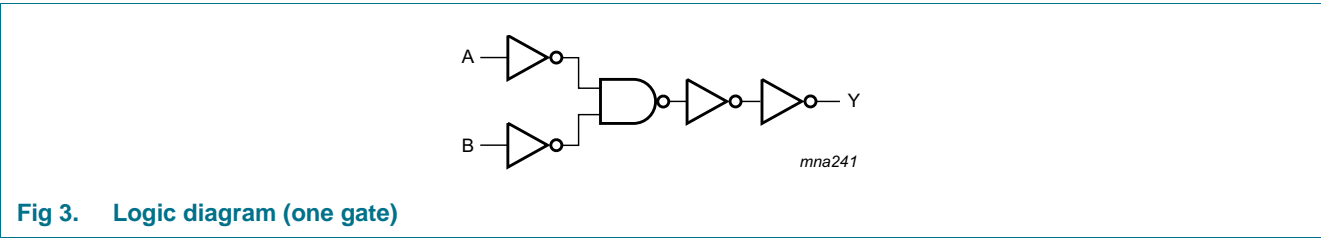
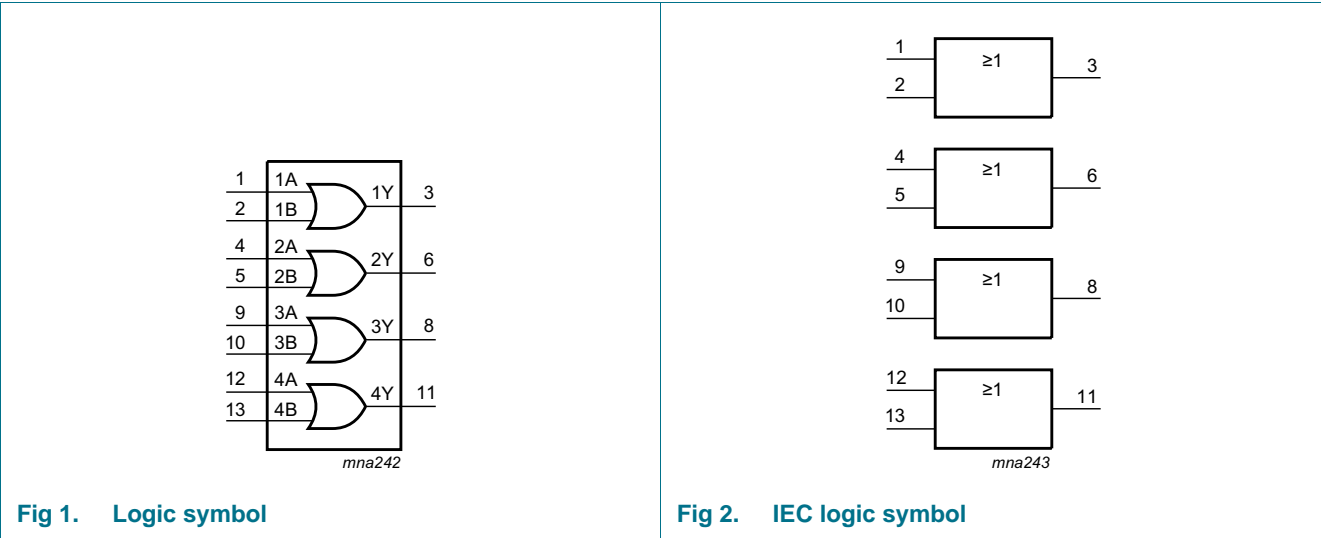
### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ALVC32D	−40 °C to +85 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74ALVC32PW	−40 °C to +85 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74ALVC32BQ	−40 °C to +85 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

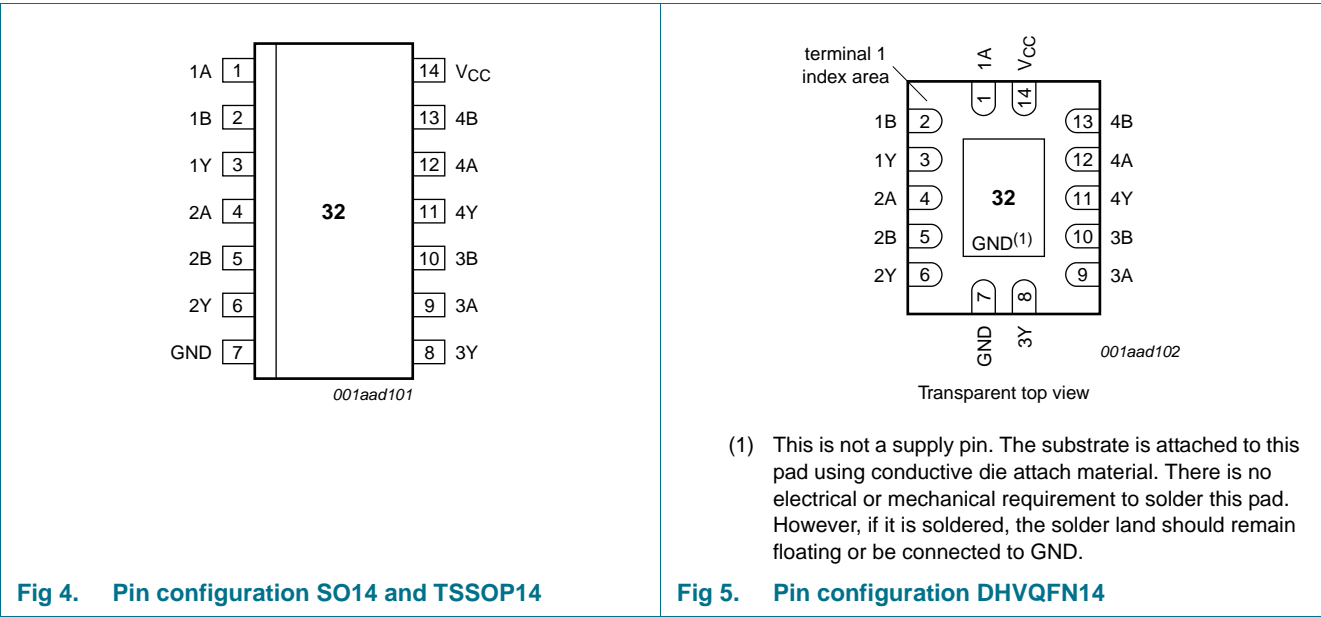


4. Functional diagram



5. Pinning information

5.1 Pinning



## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
nA	1, 4, 9, 12	data input
nB	2, 5, 10, 13	data input
nY	3, 6, 8, 11	data output
V <sub>CC</sub>	14	supply voltage
GND	7	ground (0 V)

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Input nA	Input nB	Output nY
L	L	L
L	H	H
H	L	H
H	H	H

[1] H = HIGH voltage level

L = LOW voltage level

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-50	-	mA
V <sub>I</sub>	input voltage		-0.5	+4.6	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> > V <sub>CC</sub> or V <sub>O</sub> < 0 V	-	±50	mA
V <sub>O</sub>	output voltage	output HIGH or LOW state	<sup>[1]</sup> <sup>[2]</sup> -0.5	V <sub>CC</sub> + 0.5	V
		output 3-state	-0.5	+4.6	V
		power-down mode, V <sub>CC</sub> = 0 V	<sup>[2]</sup> -0.5	+4.6	V
I <sub>O</sub>	output current	V <sub>O</sub> = 0 V to V <sub>CC</sub>	-	±50	mA
I <sub>CC</sub>	supply current		-	100	mA
I <sub>GND</sub>	ground current		-100	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +85 °C	<sup>[3]</sup> -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When V<sub>CC</sub> = 0 V (power-down mode), the output voltage can be 3.6 V in normal operation.

[3] For SO14 packages: above 70 °C derate linearly with 8 mW/K.

For TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.

For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		1.65	3.6	V
$V_I$	input voltage		0	3.6	V
$V_O$	output voltage	output HIGH or LOW state	0	$V_{CC}$	V
		output 3-state	0	3.6	V
		power-down mode; $V_{CC} = 0$ V	0	3.6	V
$T_{amb}$	ambient temperature	in free air	-40	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	0	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	10	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$T_{amb} = -40\text{ °C to }+85\text{ °C}$			Unit
			Min	Typ <sup>[1]</sup>	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	-	-	V
		$V_{CC} = 2.7$ V to 3.6 V	2.0	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	-	-	0.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = -100\text{ }\mu\text{A}$ ; $V_{CC} = 1.65$ V to 3.6 V	$V_{CC} - 0.2$	-	-	V
		$I_O = -6\text{ mA}$ ; $V_{CC} = 1.65$ V	1.25	1.51	-	V
		$I_O = -12\text{ mA}$ ; $V_{CC} = 2.3$ V	1.8	2.10	-	V
		$I_O = -18\text{ mA}$ ; $V_{CC} = 2.3$ V	1.7	2.01	-	V
		$I_O = -12\text{ mA}$ ; $V_{CC} = 2.7$ V	2.2	2.53	-	V
		$I_O = -18\text{ mA}$ ; $V_{CC} = 3.0$ V	2.4	2.76	-	V
		$I_O = -24\text{ mA}$ ; $V_{CC} = 3.0$ V	2.2	2.68	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$I_O = 100\text{ }\mu\text{A}$ ; $V_{CC} = 1.65$ V to 3.6 V	-	-	0.2	V
		$I_O = 6\text{ mA}$ ; $V_{CC} = 1.65$ V	-	0.11	0.3	V
		$I_O = 12\text{ mA}$ ; $V_{CC} = 2.3$ V	-	0.17	0.4	V
		$I_O = 18\text{ mA}$ ; $V_{CC} = 2.3$ V	-	0.25	0.6	V
		$I_O = 12\text{ mA}$ ; $V_{CC} = 2.7$ V	-	0.16	0.4	V
		$I_O = 18\text{ mA}$ ; $V_{CC} = 3.0$ V	-	0.23	0.4	V
		$I_O = 24\text{ mA}$ ; $V_{CC} = 3.0$ V	-	0.30	0.55	V
$I_I$	input leakage current	$V_{CC} = 3.6$ V; $V_I = 3.6$ V or GND	-	$\pm 0.1$	$\pm 5$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_{CC} = 0$ V; $V_I$ or $V_O = 0$ V to 3.6 V	-	$\pm 0.1$	$\pm 10$	$\mu\text{A}$

**Table 6.** Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			Unit
			Min	Typ <sup>[1]</sup>	Max	
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	0.2	10	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>CC</sub> = 3.0 V to 3.6 V; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A	-	5	750	μA
C <sub>I</sub>	input capacitance		-	3.5	-	pF

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

## 10. Dynamic characteristics

**Table 7.** Dynamic characteristicsVoltages are referenced to GND (ground = 0 V). For test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			Unit
			Min	Typ <sup>[1]</sup>	Max	
t <sub>pd</sub>	propagation delay	CP to Qn; see <a href="#">Figure 6</a> <sup>[2]</sup>				
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	2.8	4.7	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.0	3.1	ns
		V <sub>CC</sub> = 2.7 V	1.0	2.2	2.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	2.0	2.8	ns
C <sub>PD</sub>	power dissipation capacitance	per gate; V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 3.3 V <sup>[3]</sup>	-	25	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C[2] t<sub>pd</sub> is the same as t<sub>PHL</sub> and t<sub>PLH</sub>.[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).P<sub>D</sub> = C<sub>PD</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>i</sub> × N + Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) where:f<sub>i</sub> = input frequency in MHz; f<sub>o</sub> = output frequency in MHzC<sub>L</sub> = output load capacitance in pFV<sub>CC</sub> = supply voltage in Volts

N = number of inputs switching

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs

11. Waveforms

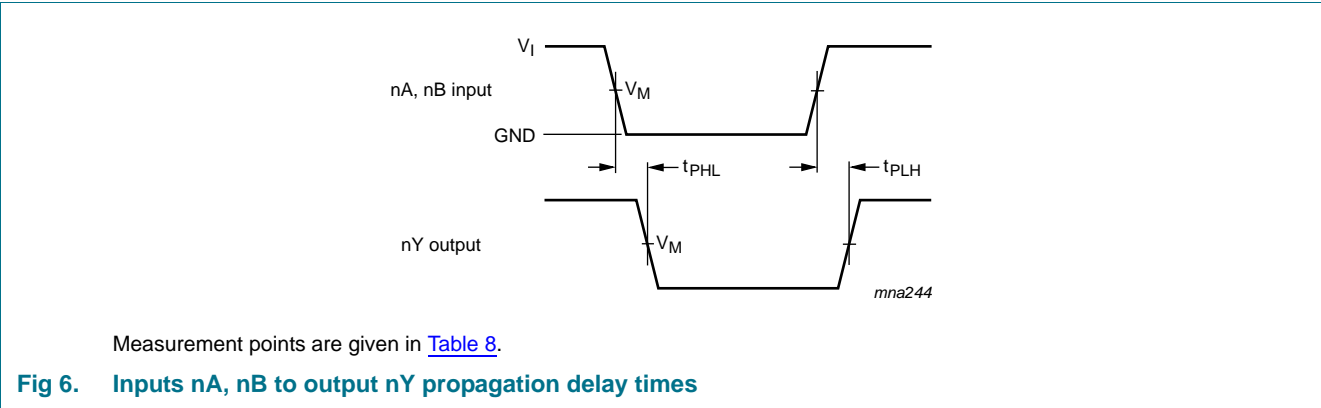
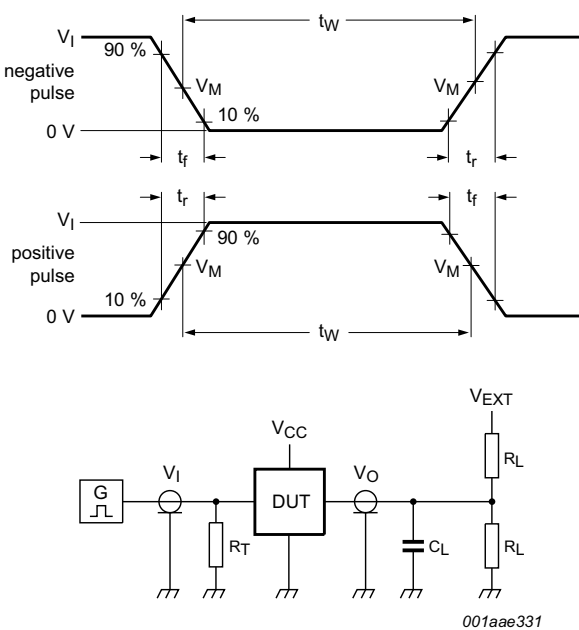


Table 8. Measurement points

Supply voltage $V_{CC}$	Input $V_I$	$V_M$
1.65 V to 1.95 V	$V_{CC}$	$0.5V_{CC}$
2.3 V to 2.7 V	$V_{CC}$	$0.5V_{CC}$
2.7 V	2.7 V	1.5 V
3.0 V to 3.6 V	2.7 V	1.5 V



Test data is given in [Table 9](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 7. Test circuitry for measuring switching times**

**Table 9. Test data**

Supply voltage $V_{CC}$	Input		Load		$V_{EXT}$		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PLZ}, t_{PZL}$	$t_{PHZ}, t_{PZH}$
1.65 V to 1.95 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	1 k $\Omega$	open	$2 \times V_{CC}$	GND
2.3 V to 2.7 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	500 $\Omega$	open	$2 \times V_{CC}$	GND
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	6 V	GND
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	6 V	GND

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

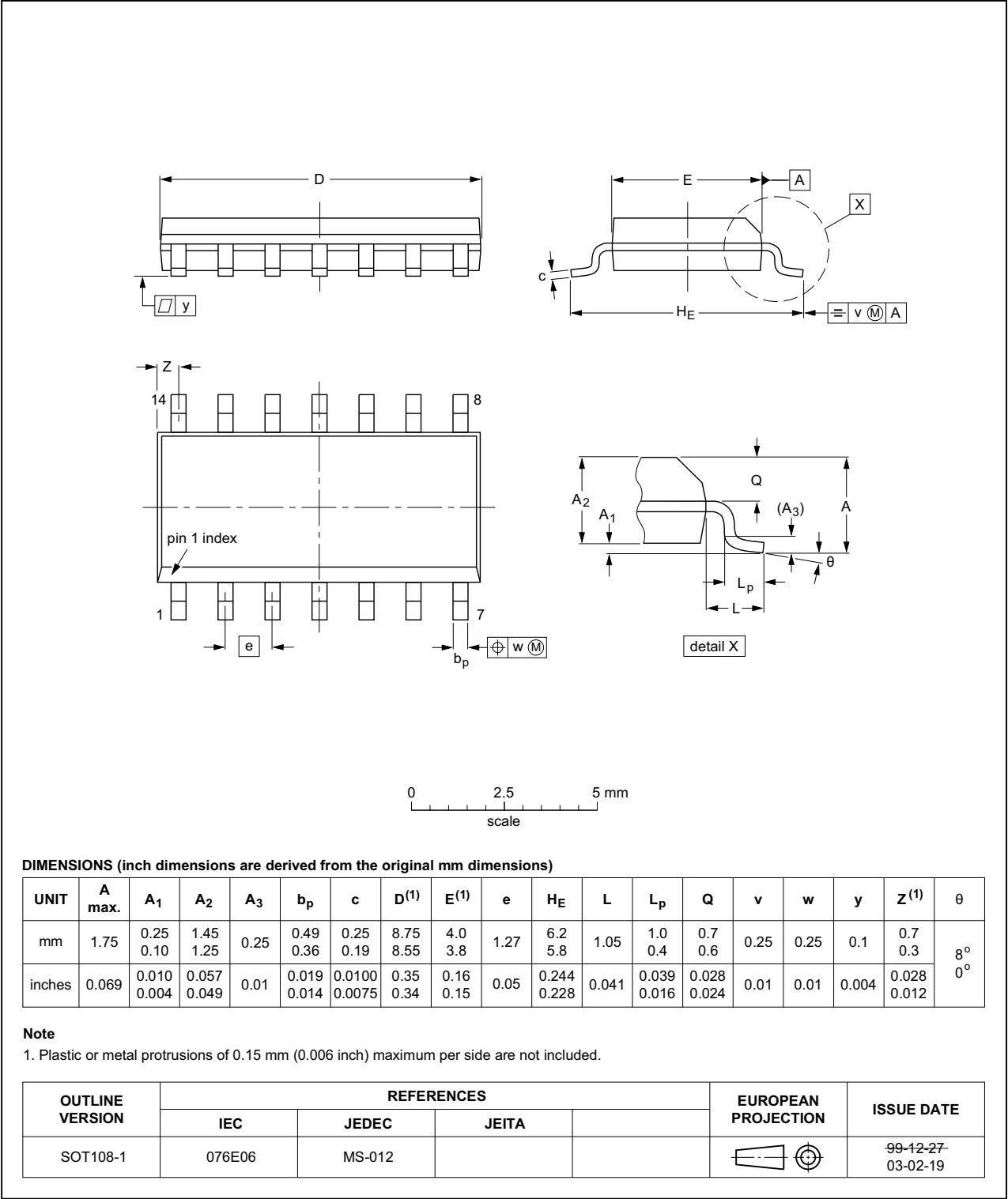


Fig 8. Package outline SOT108-1 (SO14)



TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

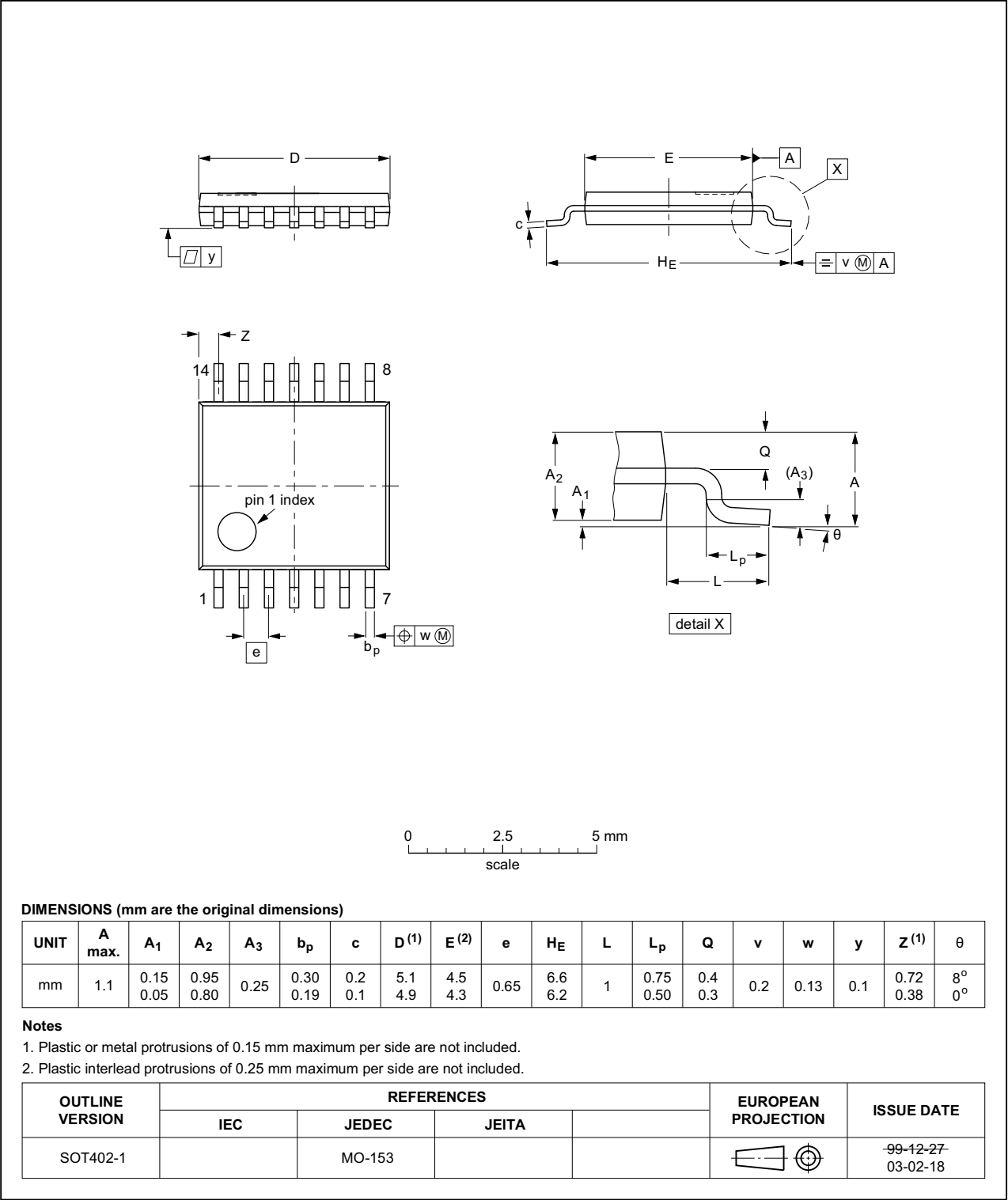


Fig 9. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

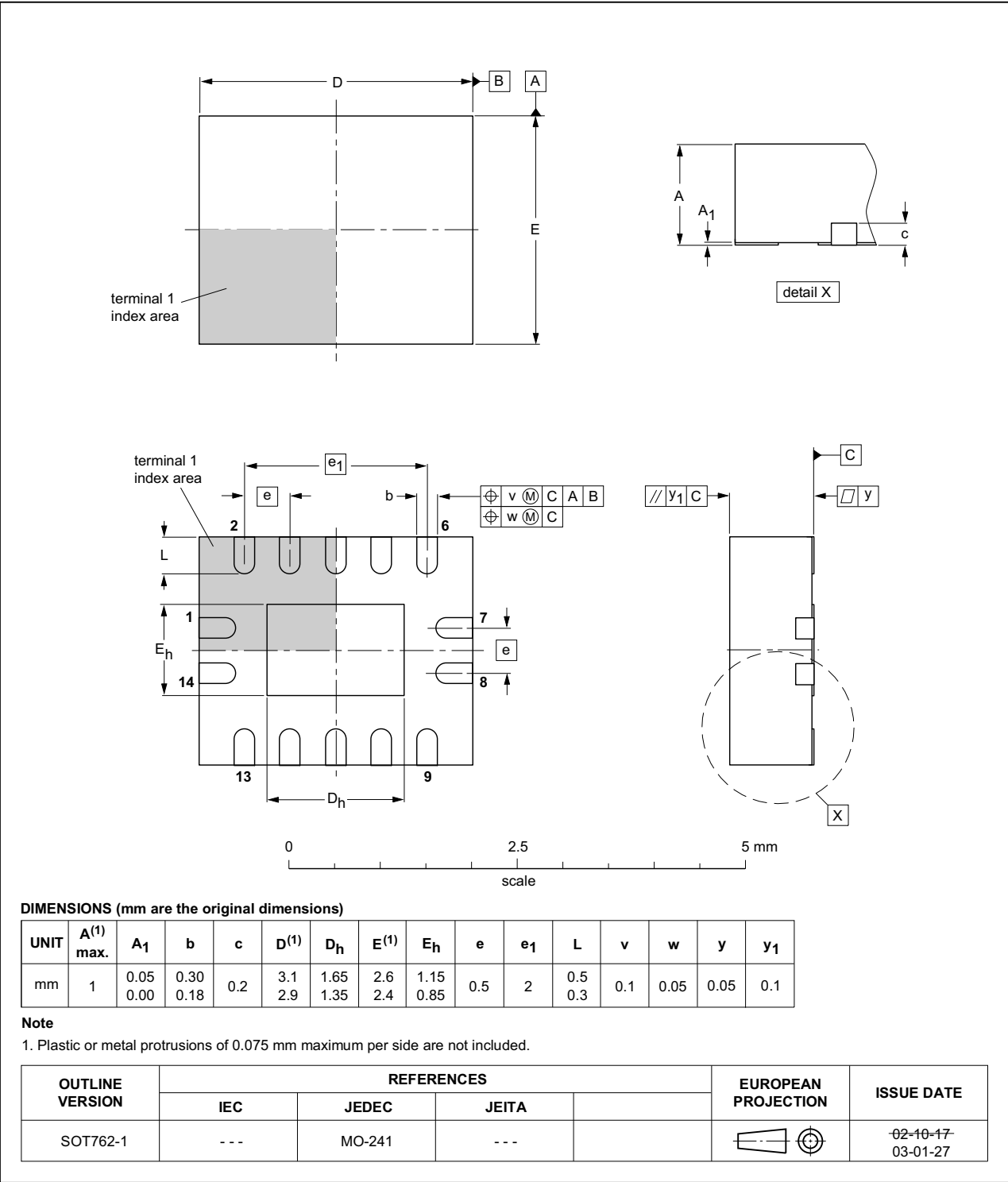


Fig 10. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVC32 v.3	20140120	Product data sheet	-	74ALVC32 v.2
<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>				
74ALVC32 v.2	20071210	Product data sheet	-	74ALVC32 v.1
74ALVC32 v.1	20021115	Product specification	-	-

## 15. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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